BGA616 Silicon Germanium Broadband MMIC Amplifier

RF & Protection Devices



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BGA616, Silicon Germanium Broadband MMIC Amplifier

Revision History: 2011-09-02, Rev. 2.1

Previous Version: 2003-04-16				
Page	Subjects (major changes since last revision)			
All	New Chip Version with integrated ESD protection			
5	Electrical Characteristics slightly changed			
7-8	Figures updated			
All	Document layout change			

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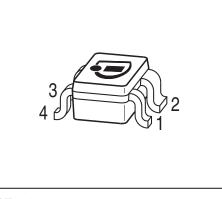
Silicon Germanium Broadband MMIC Amplifier

1 Silicon Germanium Broadband MMIC Amplifier

Feature

- Cascadable 50 Ω-gain block
- 3 dB-bandwidth: DC to 2.7 GHz with 19.0 dB typical gain at 1.0 GHz
- Compression point P_{-1dB} = 18 dBm at 2.0 GHz
- Noise figure $F_{50\Omega}$ = 2.60 dB at 2.0 GHz
- Absolute stable
- 70 GHz $f_{\rm T}$ Silicon Germanium technology
- 1 kV HBM ESD protection (Pin-to-Pin)
- Pb-free (RoHS compliant) package

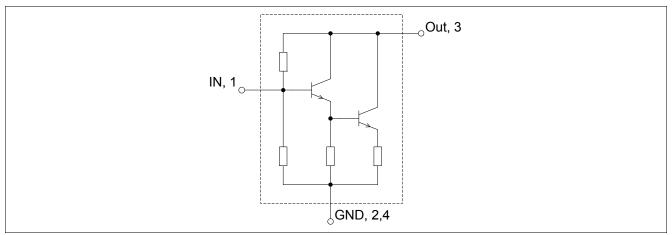




SOT343

Applications

- Driver amplifier for GSM/PCS/SCDMA/UMTS
- Broadband amplifier for SAT-TV & LNBs
- Broadband amplifier for CATV





Description

The BGA616 is a broadband matched general purpose MMIC amplifier in a Darlington configuration. It is optimized for a typical supply current of 60 mA.

The BGA616 is based on Infineon Technologies' B7HF Silicon Germanium technology.

Туре	Package	Marking
BGA616	SOT343	BPs

Note: **ESD:** Electrostatic discharge sensitive device, observe handling precaution



Electrical Characteristics

Maximum Ratings

Table 1 Maximum ratings

Parameter	Symbol	Limit Value	Unit	
Device voltage	VD	4.5	V	
Device current	ID	80	mA	
Current into pin In	I _{in}	0.7	mA	
Input power ¹⁾	$P_{\rm in}$	10	dBm	
Total power dissipation, $T_{\rm S}$ < 78 °C ²⁾	P _{tot}	360	mW	
Junction temperature	T_{J}	150	°C	
Ambient temperature range	T _A	-65 150	°C	
Storage temperature range	T _{STG}	-65 150	°C	
ESD capability all pins (HBM: JESD22-A114)	V _{ESD}	1000	V	
	1			

1) Valid for $Z_{\rm S}$ = $Z_{\rm L}$ = 50 Ω , $V_{\rm CC}$ = 6 V, $R_{\rm Bias}$ = 33 Ω

2) $T_{\rm S}$ is measured on the ground lead at the soldering point

Note: All Voltages refer to GND-Node

Thermal resistance

Table 2Thermal resistance

Parameter	Symbol	Value	Unit
Junction - soldering point ¹⁾	R _{thJS}	200	K/W

1) For calculation of $R_{\rm thJA}$ please refer to Application Note Thermal Resistance

2 Electrical Characteristics

Electrical characteristics at T_A = 25 °C (measured in test circuit specified in Figure 2) V_{CC} = 6 V, R_{Bias} = 33 Ω , Frequency = 2 GHz, unless otherwise specified

Table 3 Electrical Characteristics

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Insertion power gain	S ₂₁ ²		20.0		dB	<i>f</i> = 0.1 GHz
			19.0		dB	<i>f</i> = 1 GHz
			18.0		dB	<i>f</i> = 2 GHz
Noise figure ($Z_{\rm S}$ = 50 Ω)	$F_{50\Omega}$		2.2		dB	<i>f</i> = 0.1 GHz
			2.5		dB	<i>f</i> = 1 GHz
			2.6		dB	<i>f</i> = 2 GHz
Output power at 1 dB gain compression	P _{-1dB}		18		dBm	
Output third order intercept point	OIP ₃		29		dBm	
Input return loss	<i>RL</i> _{in}		15		dB	
Output return loss	<i>RL</i> _{out}		15		dB	
Total device current	ID		60		mA	



Electrical Characteristics

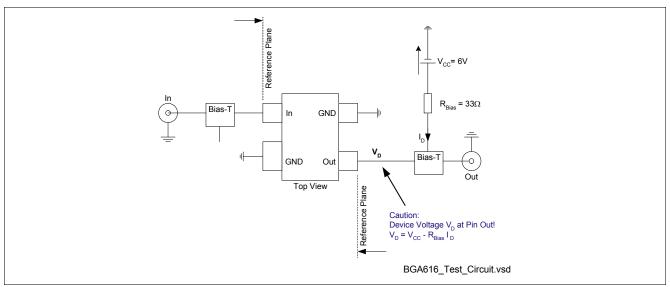
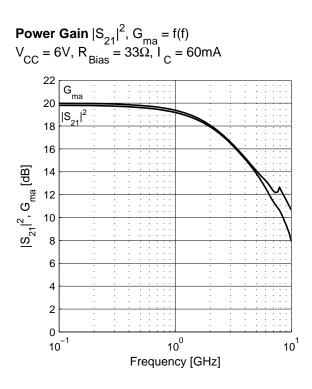


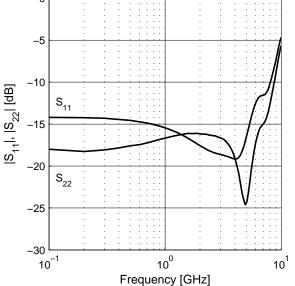
Figure 2 Test Circuit for Electrical Characteristics and S-Parameter



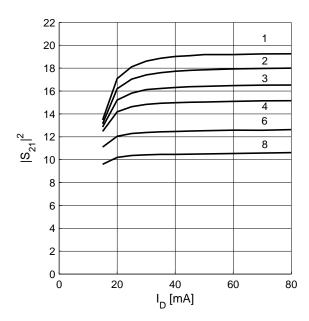
3 Measured Parameters



Matching $|S_{11}|$, $|S_{22}| = f(f)$ $V_{CC} = 6V$, $R_{Bias} = 33\Omega$, $I_C = 60mA$

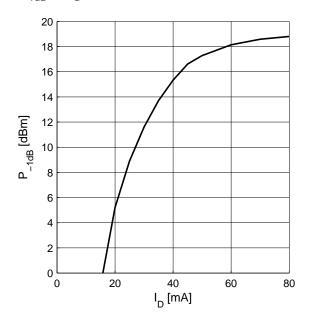


Power Gain $|S_{21}| = f(I_D)$ f = parameter in GHz



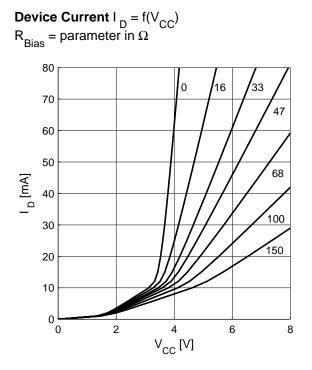
Output Compression Point

 $P_{-1dB} = f(I_D), f = 2GHz$





Measured Parameters



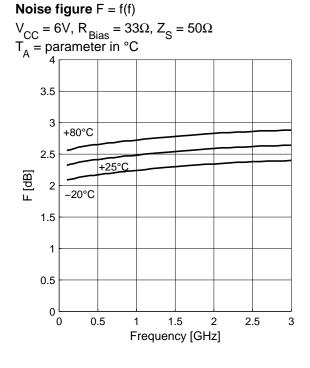
I _D [mA]

T_A[°C]

Device Current I $_{D} = f(T_{A})$ V_{CC} = 6V, R_{Bias} = parameter in Ω

40 L -40

-20





Package Information

4 Package Information

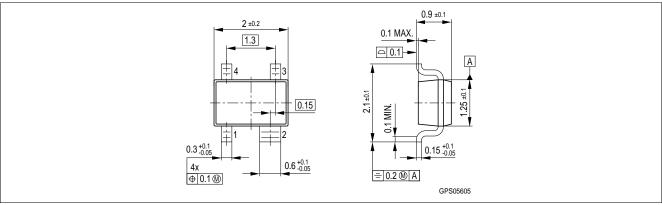


Figure 3 Package Outline SOT343

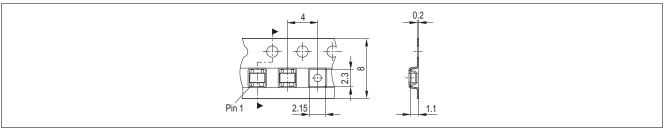


Figure 4 Tape for SOT343

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